IN THE CLAIMS:

Claims 1 through 6 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1.   (Currently Amended) A method of enhancing adhesion of a compound to a surface of a substrate comprising:

providing ~~the~~ a semiconductor substrate having the surface;

finding irregularities to remove from the semiconductor substrate by scanning the semiconductor substrate to locate irregularities; and

roughening the surface of the semiconductor substrate when removing irregularities.

2.   (Currently Amended) The method according to claim 1, wherein roughening comprises removing contamination and foreign particles from the surface of the semiconductor substrate.

3.   (Currently Amended) A method of enhancing adhesion of a material to a surface of a substrate comprising:

providing ~~the~~ a semiconductor substrate having the surface;

determining irregularities to remove from the semiconductor substrate by scanning the semiconductor substrate; and

roughening the surface of the semiconductor substrate while removing irregularities.

4. (Currently Amended) The method according to claim 3, wherein roughening comprises removing contamination and foreign particles from the surface of the <u>semiconductor</u> substrate.

5. (Currently Amended) A method for improving adhesion of a compound to a surface of a substrate comprising:

providing <u>a semiconductor</u> ~~the~~ substrate having the surface;

locating irregularities to be removed from the <u>semiconductor</u> substrate by scanning the <u>semiconductor</u> substrate ; and

roughening the surface of the <u>semiconductor</u> substrate while removing irregularities from the <u>semiconductor</u> substrate.

6. (Currently Amended) The method according to claim 5, wherein roughening comprises removing contamination and foreign particles from the surface of the <u>semiconductor</u> substrate.